

NTR4170N

Power MOSFET

30 V, 3.2 A, Single N-Channel, SOT-23

Features

- Low $R_{DS(on)}$
- Low Gate Charge
- Low Threshold Voltage
- Halide Free
- This is a Pb-Free Device

Applications

- Power Converters for Portables
- Battery Management
- Load/Power Switch

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DSS}	30	V
Gate-to-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current (Note 1)	I_D	$t \leq 30$ s, $T_A = 25^\circ\text{C}$	3.2
		$T_A = 85^\circ\text{C}$	2.3
		$t \leq 10$ s, $T_A = 25^\circ\text{C}$	4.0
Power Dissipation (Note 1)	P_D	Steady State, $T_A = 25^\circ\text{C}$	0.78
		$t \leq 10$ s	1.25
Pulsed Drain Current	I_{DM}	8.0	A
Operating Junction and Storage Temperature	T_J, T_{stg}	-55 to 150	$^\circ\text{C}$
Source Current (Body Diode)	I_S	0.78	A
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)	T_L	260	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

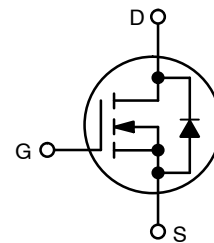
THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	260	$^\circ\text{C}/\text{W}$
Junction-to-Ambient - $t \leq 30$ s	$R_{\theta JA}$	153	
Junction-to-Ambient - $t < 10$ s (Note 1)	$R_{\theta JA}$	100	

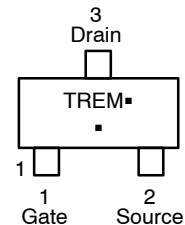
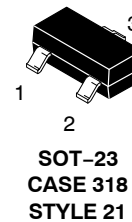
1. Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces).

$V_{(BR)DSS}$	$R_{DS(on)}$ MAX	I_D MAX
30 V	55 m Ω @ 10 V	3.2 A
	70 m Ω @ 4.5 V	2.8 A
	110 m Ω @ 2.5 V	2.0 A

SIMPLIFIED SCHEMATIC - N-CHANNEL



MARKING DIAGRAM/ PIN ASSIGNMENT



TRE = Specific Device Code
M = Date Code
▪ = Pb-Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
NTR4170NT1G	SOT-23 (Pb-Free)	3000/Tape & Reel
NTR4170NT3G	SOT-23 (Pb-Free)	10000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.



NTR4170N

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 250 μA	30			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} / T _J	I _D = 250 μA, Reference to 25°C		26.4		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = 24 V, T _J = 25°C V _{GS} = 0 V, V _{DS} = 24 V, T _J = 125°C			1.0 5.0	μA
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±12 V			±100	nA

TY CHARACTERISTICS (Note 3)

Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = 250 μA	0.6	1.0	1.4	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} / T _J			3.3		mV/°C
Drain-to-Source On-Resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 3.2 A		45	55	mΩ
		V _{GS} = 4.5 V, I _D = 2.8 A		50	70	
		V _{GS} = 2.5 V, I _D = 2.0 A		64	110	
Forward Transconductance	g _{FS}	V _{DS} = 5.0 V, I _D = 3.2 A		8.0		S

CHARGES, CAPACITANCES AND GATE RESISTANCE

Input Capacitance	C _{iss}	V _{GS} = 0 V, f = 1.0 MHz, V _{DS} = 15 V		432		pF
Output Capacitance	C _{oss}			53.6		
Reverse Transfer Capacitance	C _{rss}			37.1		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 4.5 V, V _{DS} = 15 V, I _D = 3.2 A		4.76		nC
Threshold Gate Charge	Q _{G(TH)}			0.3		
Gate-to-Source Charge	Q _{GS}			1.0		
Gate-to-Drain Charge	Q _{GD}			1.4		
Gate Resistance	R _G			3.8		Ω

SWITCHING CHARACTERISTICS, V_{GS} = 4.5 V (Note 4)

Turn-On Delay Time	t _{d(on)}	V _{GS} = 4.5 V, V _{DD} = 15 V, I _D = 3.2 A, R _G = 6.2 Ω		6.4		ns
Rise Time	t _r			9.9		
Turn-Off Delay Time	t _{d(off)}			15.1		
Fall Time	t _f			3.5		

DRAIN-SOURCE DIODE CHARACTERISTICS

Forward Diode Voltage	V _{SD}	V _{GS} = 0 V, I _S = 1.0 A, T _J = 25°C		0.75	1.0	V
Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, I _S = 1.0 A, dI _{SD} /dt = 100 A/μs		8.0		ns
Charge Time	t _a			5.1		
Discharge Time	t _b			2.9		
Reverse Recovery Charge	Q _{RR}			2.9		nC

2. Surface-mounted on FR4 board using 1 in sq pad size (CU area = 1.127 in sq [2 oz] including traces).

3. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.

4. Switching characteristics are independent of operating junction temperatures.